



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4473G V53		<b>Issued</b>		2. August 2018			
<b>MA#</b>		MA001078718							
<b>Package</b>		PG-DSO-12-11		<b>Weight*</b>		405.18 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.080	1.99	1.99	19942	19942	
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		569		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		171		
	non noble metal	copper	7440-50-8	230.106	56.78	56.86	567905	568645	
wire	non noble metal	aluminium	7429-90-5	0.137	0.03	0.03	337	337	
encapsulation	organic material	carbon black	1333-86-4	0.307	0.08		758		
	plastics	epoxy resin	-	14.130	3.49		34872		
	inorganic material	silicondioxide	60676-86-0	139.145	34.34	37.91	343412	379042	
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10453	10453	
plating	inorganic material	phosphorus	7723-14-0	0.002	0.00		4		
	non noble metal	nickel	7440-02-0	0.630	0.16	0.16	1555	1559	
solder	noble metal	silver	7440-22-4	0.203	0.05		501		
	non noble metal	tin	7440-31-5	0.162	0.04		400		
	non noble metal	lead	7439-92-1	7.747	1.91	2.00	19121	20022	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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